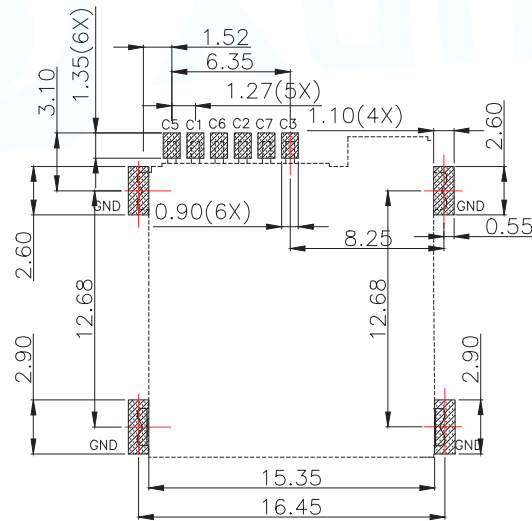
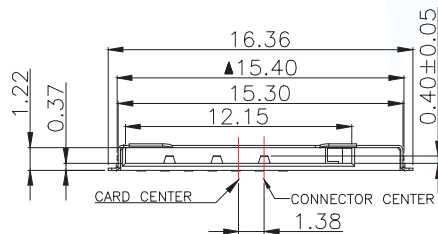


**MATERIAL:**  
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,UL 94V-0  
 CONTACT: COPPER ALLOY  
 SHELL: SUS

**PLATING:**  
 CONTACT: PLATED 50U" NI OVER ALL CONTACT AU 1U  
 SHELL: PLATED 50U" NI OVERALL  
 PLATED 1U" AU SELECTIVE CONTACT AREA

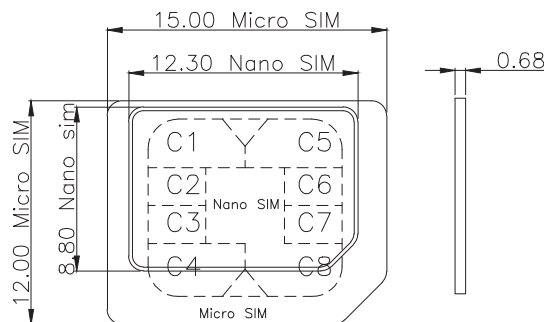
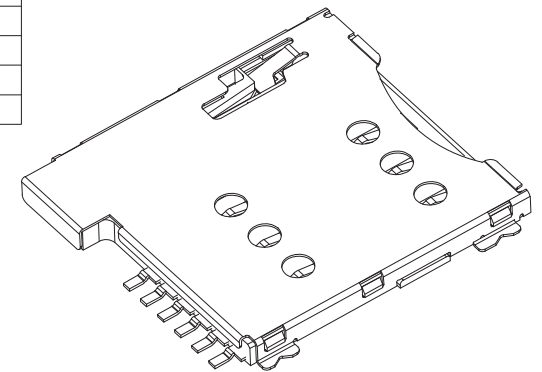
**ELECTRICAL:**  
 CURRENT RATING: 0.5MA  
 VOLTAGE RATING: 5V AC/DC  
 AMBIENT TEMPERATURE RANGE: -20℃ ~ +60℃  
 STORAGE TEMPERATURE RANGE: -40℃ ~ +85℃  
 AMBIENT HUMIDITY RANGE: 95% R.H. MAX.  
 CONTACT RESISTANCE: 100M MAX.Ω  
 INSULATION RESISTANCE: 1000M MIN./500VDCΩ  
 REFLOW PEAK TEMP: 260℃  
 MATING CYCLES: 5000MIN INSERTIONS



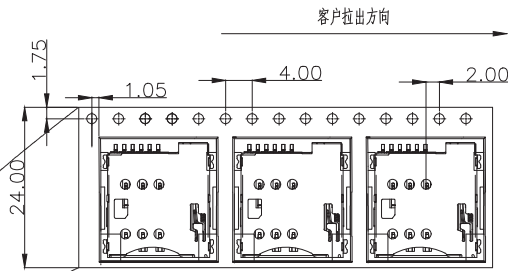
▨ PAD AREA  
 ■ KEEP OUT AREA

RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE ±0.05

MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

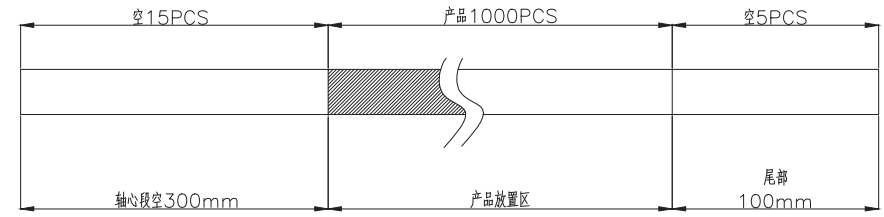


MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MICRO SIM CARD PUSH 6PIN H1.35	
DECIMALS:	ANGLES:±1'		PAR	SMC-202-ARP6
X.X:±0.15			DWN	
X.XX:±0.10			CHKD	
X.XXX:±0.05		APVD		
CUSTOMER COPY		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
			REV:A	

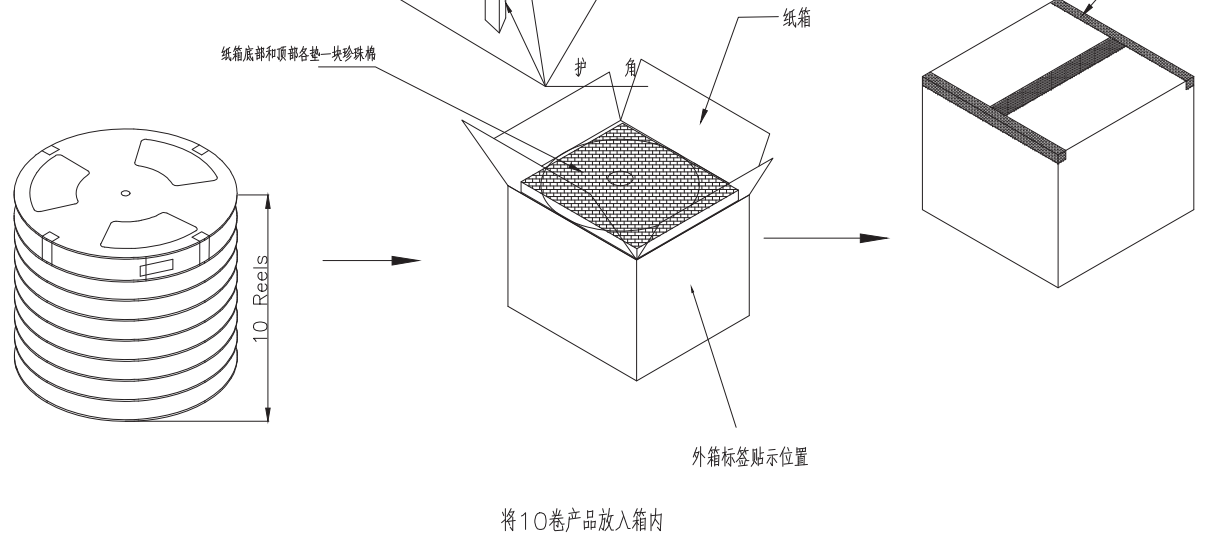
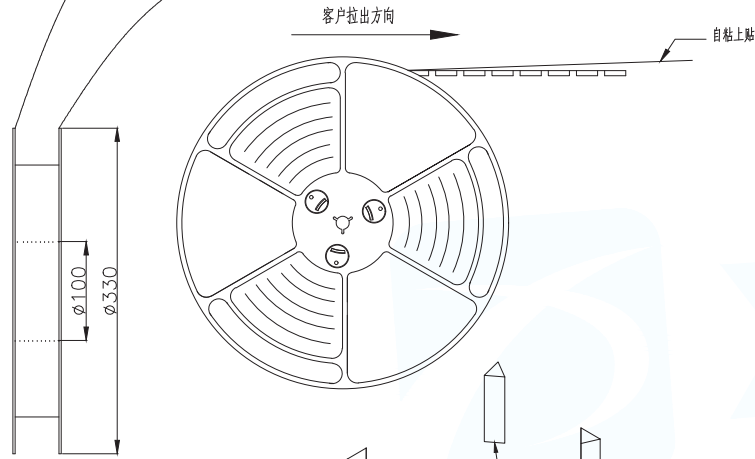


NOTES

1. 每卷包装数量: 1000PCS/每卷
2. 卷带包装方式:



3. 每箱包装数量: 10000PCS/箱
4. 纸箱 350mm\*350mm\*440mm (内部尺寸), 材质K=K



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: MICRO SIM CARD PUSH PUSH 6PIN H1.35 包装图	
		PAR	SMC-202-ARP6
DECIMALS:		DWN	
ANGLES: ±1°		CHKD	
X.X: ±0.15		APVD	
X.XX: ±0.10		SCALE 1:1	UNIT: MM
X.XXX: ±0.05		SIZE: A4	SHEET: 1F1
CUSTOMER COPY			REV: A